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| Date Received : (OTC use only) | Rensselaer Polytechnic Institute**Invention Disclosure Form**(revised 05/23/2014) | Case No.: (OTC use only) |

The Office of Technology Commercialization (OTC) reviews all invention disclosure forms as they are received from members of the Rensselaer community. Where appropriate, the OTC endeavors to license Rensselaer inventions to industry for further development and commercialization. Rensselaer will share income derived from the invention with the inventor(s) according to its standard policies.

The purpose of this form is to notify the OTC of your potential invention and any relevant sponsorship and publication history. The form also serves to establish a legal record of the date of conception of the invention. This form should be submitted to the OTC when a new and useful invention has been conceived or developed.

**Use as much space as needed to complete this form. When complete, submit to the Office of Technology Commercialization via e-mail:** **otc@rpi.edu****.** **Submissions are considered normal business days, M-F.**

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| * 1. **Title of Invention.** Usea brief descriptive title to aid in identifying the technology.
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| * 1. **Contributors.** An inventor, creator, or contributor, as used herein, is an individual who has conceived or provided an essential element of the invention, either independently or jointly with others, during the evolution of the technology concept or its reduction to practice. Please place Asterisk (\*) next to primary contact.
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| CONTRIBUTOR | WORK CONDUCTED AT | AFFILIATION/POSITION | DEPARTMENT/PHONE |
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| **Non-Rensselaer Contributor(s)** (if listed above) |
| a. With respect to the concept of the invention, in detail, what did the Rensselaer contributors contribute? |
| b. With respect to the concept of the invention, in detail, what did the non-Rensselaer contributors contribute? (include dates) |

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| * 1. **Research Funding Support Report.** The invention was made under one or more of the following circumstances [check all that apply]:
 |
| [ ]  In connection with Federal, State, commercial and/or other externally-sponsored research. If so, please identify source(s) and contract number(s) below:

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| --- | --- | --- |
| Rensselaer Fund Number | Agency/Company | Contract Number(s) |
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[ ]  Prime to the agency/company [ ]  Under a subcontract with \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_[ ]  Internal funding (e.g. school and/or departmental, start-up or seed funding)[ ]  Independent research conducted at Rensselaer (no internal/external funds) but with “Significant Use of Rensselaer Support,” per the IP Policy. |

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| * 1. **Description of the Invention.** Please use extra space if needed and attach any additional information (e.g. data, publications, graphs, presentations). Please note that any attachments, while encouraged, **are only supporting materials**. The form will be considered **incomplete** without the following questions answered.

For an example of a completed disclosure, go to: <http://www.patentapplications.net/disclosure/samp_dis.html>  |
| 1. **Rationale.** Why did you come up with this innovation or conduct the research that lead to your invention? (Highlight problems you see with current technology solutions)
 |
| 1. **Brief Description**. Briefly describe your invention. (How have you overcome the problems with the current method/system/device?)
 |
| 1. **Novelty**. What is the unique part of your invention? Distinguish your invention from what is already known.
 |
| 1. **Purpose**. What advantages over current technology does your invention possess?
 |
| 1. **Limitations.** Does the invention have any problems or limitations of its own? Can they be overcome? How?
 |
| 1. **Utility**. What are the possible applications of the invention? Are there any other uses that might be realized in the future?
 |
| 1. **Experimental Verification.** Have you tested the invention? If yes, please describe. Have you constructed a prototype?
 |
| 1. **Date of conception of invention**. \_\_\_\_\_\_\_ / \_\_\_\_\_\_\_ / \_\_\_\_\_\_\_\_

 Has this date been documented? [ ] Yes [ ] No |
| 1. **Supporting Materials.** Please provide at least one sketch of the invention and any supplemental material (e.g. presentations, papers)
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| * 1. **Public Disclosures\***
 |
| 1. Please identify any disclosures, either written or oral, of the invention that you have **already** made to others.

Date:  Title of publication/ presentation:  Journal name or audience of presentation: |
| 1. Please identify any disclosures, either written or oral, of the invention that you expect to make to others in the **future**.

 Expected date:  Title of publication/presentation::  Journal name or audience of presentation:  |

\*Please keep your OTC Licensing Associate informed of any future submission or acceptance for publication or other possible non-confidential disclosure of any manuscript(s), abstract(s) or oral presentation(s) describing the invention—such activities can adversely affect patent rights.

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| * 1. **Commercialization**
 |
| 1. What companies do you believe would be interested in commercializing the invention?
 |
| 1. Have you worked with/been approached by any companies regarding the invention? If yes, which companies?
 |
| 1. Identify similar products by names and manufacturers.
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| * 1. **Background Information**
 |
| 1. Are laboratory records and data available? Give reference numbers and physical location, but do not enclose documentation.
 |
| 1. Was PatentSafe used? (Electronic lab notebook available to researchers at RPI) [ ] Yes [ ] No
 |
| 1. List below related patents known to the inventor:
 |
| 1. List the most relevant articles, journals, or abstracts of other authors:
 |
| 1. Are the inventors aware of any other Institute patents or potentially patentable inventions developed at the Institute or under development at the Institute that may be required to practice the invention disclosed herein?)

[ ] Yes [ ] No If yes, describe: |
| 1. Keywords. Please list specific keywords that could be used in performing a patent search of this technology.
 |

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| * 1. **Marketing Abstract** – Please provide a brief, **non-confidential,** practical, marketing abstract of the invention. Note this abstract is intended for marketing purposes under non-confidential situations. Do not include anything that would allow someone to practice the invention or that may be a claim in the patent application. Describe the problem solved and advantages of this technology over existing technologies. Ex: <http://www.rpitechnology.com/attachments/UNAfold_Mkt_Lead.pdf>
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| * 1. **Technology Area and Keywords.**  Please identify the market applications and key words that best characterize the invention. [Check all that apply.]
 |

**ENGINEERING**

[ ] Aeronautical Engineering

[ ] Architecture

[ ] Chemical Engineering

[ ] Communication Engineering

[ ] Biomedical Engineering

[ ] Civil Engineering

[ ] Electrical Engineering

[ ] Industrial Engineering

[ ] Mechanical Engineering

[ ] Nuclear Engineering

**PHYSICAL SCIENCE**
[ ] Acoustics

[ ] Adhesive

[ ] Alternative Energy

[ ] Automation

[ ] Batteries

[ ] Building

[ ] CAD

[ ] CAM

[ ] Catalyst

[ ] Ceramics

[ ] Chemistry

[ ] Coatings

[ ] Composites

[ ] Database

[ ] Design

[ ] Effluent Treatment

[ ] Elastomers

[ ] Electrical Power

[ ] Electrochemistry

[ ] Electronics
[ ] E[nergy](http://otlportal.stanford.edu/techfinder/keyword_search/category%3Denergy/type%3Dphysci/ref%3DUREF12822021720110277100/A11110277141)
[ ] Environment

[ ] Food Chemistry

[ ] Fuel Cells

[ ] Exhaust Treatment

[ ] Games

[ ] Gels

[ ] Geology

[ ] Glass

[ ] Hardware

[ ] Imaging\*\*

[ ] Industrial Design

[ ] Informatics\*\*

[ ] Information Technology\*\*
[ ] Instrumentation

[ ] Integrated Chips

[ ] Interconnects
[ ] Internet\*\*

[ ] LED

[ ] Lighting/Illumination
[ ] M[aterials](http://otlportal.stanford.edu/techfinder/keyword_search/category%3Dmaterials/type%3Dphysci/ref%3DUREF12822021720110277100/A1111027714)

[ ] Measurement Systems
[ ] MEMS

[ ] Monomers
[ ] Nanotechnology

[ ] Nanomaterials

[ ] Nanodevice

[ ] NEMS

[ ] Networking

[ ] Optics/Optical Systems

[ ] Optoelectronics Systems

[ ] Petroleum

[ ] Photochemistry
[ ] Photonics

[ ] Polymers

[ ] Purification

[ ] Research Tool\*\*

[ ] Robotics\*\*
[ ] Semiconductor
[ ] Sensors

[ ] Simulation and Modeling\*\*
[ ] Software\*\*

[ ] Solar Technology

[ ] Solvents

[ ] Terahertz Technology

**BIOLOGICAL**

**DIAGNOSTIC\***

[ ] Antibody

[ ] Antioxidants

[ ] Assay

[ ] In Situ

[ ] Measurement

[ ] Ultrasound

**GENOMICS**

[ ] Bioinformatics\*\*

[ ] Library

[ ] Mutation

[ ] Pharmacogenomics

[ ] Polymorphism

[ ] Positional Cloning

[ ] Proteomics

**RESEARCH TOOL**

[ ] Antibody

[ ] Bioinformatics\*\*

[ ] Cell Line

[ ] Enzyme

[ ] Equipment

[ ] Expression System

[ ] Immunoassay

[ ] HTS

[ ] Phage Display

**THERAPEUTIC**

[ ] Analgesic

[ ] Anesthetic

[ ] Angiogenesis

[ ] Antibody

[ ] Anti-inflammatory

[ ] Antimicrobial

[ ] Apoptosis

[ ] Cell Signaling

[ ] Cell Therapy

[ ] Diagnosis

[ ] Disease Model

[ ] Drug Delivery

[ ] Drug Discovery

[ ] Fertility

[ ] Gene Therapy

[ ] Hormone

[ ] Immunotherapy

[ ] Modeling

[ ] Natural Product

[ ] Peptides

[ ] Pro-drug

[ ] Prosthetics

[ ] Proteins

[ ] Surgical

[ ] Small Molecule

[ ] Surgical

[ ] Tissue Engineering

[ ] Transplant

[ ] Vaccine

[ ] Virus

[ ] Wound Healing

**MEDICAL DEVICE**

[ ] Delivery

[ ] Diagnosis

[ ] Measurement

[ ] Prosthetics

[ ] Surgical

**OTHER**

[ ] Education

[ ] Copyrighted content

[ ] Music

[ ] Occupational Hazard

[ ] Remote Operation

[ ] Safety

[ ] Video

 **\_\_\_\_\_\_\_\_\_\_\_\_\_**

**Additional Key Words:**

\* BIOLOGICAL MATERIAL – Does this disclosure include biological matter [ ] Yes [ ] No
 If yes, Please attach a list of materials for reference

 \*\* SOFTWARE – Does this disclosure include a software element, or is software

 implemented in the invention. If yes, please complete the Software

 Supplemental Disclosure Form which can be found at [www.rpitechnology.com](http://www.rpitechnology.com) [ ] Yes [ ] No

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| **Inventor Declaration** |
| I (we) hereby assign all my (our) rights, title, and interest to this Invention to Rensselaer Polytechnic Institute, and agree to execute as requested any patent applications, additional assignments and other documents related to this Invention and to cooperate with Rensselaer Polytechnic Institute in the protection of this Invention. The undersigned also hereby declare(s) that he/she/they are the true originator(s) of the Invention disclosed herein, and that the Invention arose in the course of work on behalf of Rensselaer Polytechnic Institute or through the benefit of the use of Rensselaer facilities, equipment, or other resources. By submitting this disclosure, the individuals named below hereby declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true. If there are more than four contributors, please attach additional forms. |
|  |
| **Signature of Inventor(s)** *All inventors must sign* |
|  |  |
| **Contributor 1** |  |
|  Signature |  |
|  Date |  | Print Full Name (First, Middle, Last) |  |
| RPI ID# |  | RPI Dept. |  |
| Country of Citizenship |  | Date of Birth 1 (Month/Day) |  |
| Permanent Home Address |  |
| Permanent Email Address |  |
| Other Email Address |  |
| Office Phone |  |
| Status (select one) | Faculty | **[ ]**  | Staff | **[ ]**  | Student |  **[ ]**  | Other  **[ ]**  |
| Other Institution Name, Address and IP Contact Info2 |  |
|  |
| **Contributor 2** |  |
|  Signature |  |
|  Date |  | Print Full Name (First, Middle, Last) |  |
| RPI ID# |  | RPI Dept. |  |
| Country of Citizenship |  | Date of Birth 1 (Month/Day) |  |
| Permanent Home Address |  |
| Permanent Email Address |  |
| Other Email Address |  |
| Office Phone |  |
| Status (select one) | Faculty | [ ]  | Staff | [ ]  | Student |  [ ]  | Other  **[ ]**  |
| Other Institution Name, Address and IP Contact Info 2 |  |
|  |
|  |
| **Contributor 3** |  |
|  Signature |  |
|  Date |  | Print Full Name (First, Middle, Last) |  |
| RPI ID# |  | RPI Dept. |  |
| Country of Citizenship |  | Date of Birth 1 (Month/Day) |  |
| Permanent Home Address |  |
| Permanent Email Address |  |
| Other Email Address |  |
| Office Phone |  |
| Status (select one) | Faculty |  [ ]  | Staff | [ ]  | Student | [ ]  | Other  **[ ]**  |
| Other Institution Name, Address and IP Contact Info 2 |  |
|  |
| **Contributor 4** |  |
|  Signature |  |
|  Date |  | Print Full Name (First, Middle, Last) |  |
| RPI ID# |  | RPI Dept. |  |
| Country of Citizenship |  | Date of Birth 1 (Month/Day) |   |
| Permanent Home Address |  |
| Permanent Email Address |  |
| Other Email Address |  |
| Office Phone |  |
| Status (select one) | Faculty | [ ]  |  Staff | [ ]  | Student | [ ]  | Other  **[ ]**  |
| Other Institution Name, Address and IP Contact Info 2 |  |
| 1. Rensselaer collects Rensselaer ID numbers and month and day of birth rather than social security numbers for security reasons. This information as well as country of citizenship is required. Absence of this information may hinder the distribution of the contributors’ share of any royalties that may result from this technology
2. If inventor is not a Rensselaer Polytechnic Institute employee, provide address of the institution or company with which he/she is associated along with their Intellectual Property contact information.
* End of Form -
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